

Pulse Part Number W9909





Ideal for board-to-antenna applications Spring contact for positive connection Surface mount technology; solder reflowable

#### Features

- PWB Footprint 3.2 x 1.7 mm
- Tape & Reel Packaging
- RoHS Compliant Product

#### **Applications**

- Antenna Contacts
- W3530 Antenna RF Contacts





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### W9909 C-Clip Configuration and Dimensions





#### PWB Pad Dimensions and C-Clip Position for W9909

C-clip position on PWB layout





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Ground Clearance Area for W9909 C-Clip





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Reel packing is used for the C-clip.



NOTE:

- 1. MATERIAL:PS Clear-Thickness:0.40±0.05mm

- 2. Packing Length Per 22' Reel: 60 Meters 3. Component Load Per 13' Reel: 5000 Pcs 4. 10 SPRECKET HELE CUMULATTIVE TELERANCE: ±0.2
- 5. CARRIER CAMBER IS WITHIN 1mm IN 100mm

Figure 2. Connector packing.



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### W9909 Connector Soldering

#### **Recommendation for reflow soldering process**

Printing stencil thickness 0.15 to 0.25 mm is recommended for the solder paste. The maximum soldering temperature should not exceed 260°C.

The temperature profile recommendations for reflow solder process are presented in Figure 1 and 2. The reflow profile presented in Figure 2 describes maximum reflow temperatures.

Figure 1 - Minimum temperature profile recommendation for reflow soldering process

	Method of heat transfer	Controlled hot air convection
1	Average temperature gradient in preheating	2.5°C/s
2	Soak time	2-3 minutes
3	Max temperature gradient in reflow	3°C/s
4	Time above 217°C	Max 30 sec
5	Peak temperature in reflow	230°C for 10 seconds
6	Temperature gradient in cooling	Max -5°C/s





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Method of heat transfer Average temperature gradient in preheating	Controlled hot air convection 2.5°C/s
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Soak time	2-3 minutes
Max temperature gradient in reflow	3°C/s
Time above 217°C	Max 60 sec
Time above 230°C	Max 50 sec
Time above 250°C	Max 10 sec
Peak temperature in reflow	260°C for 5 seconds
Temperature gradient in cooling	Max -5°C/s
	Time above 217°C Time above 230°C Time above 250°C

Figure 2 - Maximum temperature profile recommendation for reflow soldering process





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## SMT notes



Pick & Place area







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### SMT setup recommendation



